SONY

Diagonal 8mm (Type 1/2) Progressive Scan CCD Image Sensor with Square Pixel for B/W Cameras

ICX267AL

Description

The ICX267AL is a diagonal 8mm (Type 1/2) interline CCD solid-state image sensor with a square pixel array and 1.45M effective pixels. Progressive scan allows all pixels' signals to be output independently. Also, the adoption of high frame rate readout mode supports 30 frames per second. This chip features an electronic shutter with variable charge-storage time which makes it possible to realize full-frame still image without a mechanical shutter. High resolution and high low dark current are achieved through the adoption of HAD (Hole-Accumulation Diode) sensors.

(Applications: Electronic still cameras, PC input cameras, etc.)

Features

- ◆ Progressive scan allows individual readout of the image signals from all pixels.
- ◆ High horizontal and vertical resolution (both approx. 1024TV-lines) still image without a mechanical shutter.
- ◆ Supports high frame rate readout mode (effective 512 lines output, 30 frames/s)
- ◆ Square pixel
- ◆ Horizontal drive frequency: 28.636MHz
- ♦ No voltage adjustments (Reset gate and substrate bias need no adjustment.)
- ◆ High resolution, high color reproductivity, high sensitivity, low dark current
- ◆ Low smear, excellent antiblooming characteristics
- ◆ Continuous variable-speed shutter

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Device Structure

◆ Interline CCD image sensor

♦ Image size : Diagonal 8mm (Type 1/2)

◆ Total number of pixels
★ Number of effective pixels
∴ 1434 (H) × 1050 (V) approx. 1.50M pixels
∴ 1392 (H) × 1040 (V) approx. 1.45M pixels

♦ Number of active pixels : 1360 (H) × 1024 (V) approx. 1.40M pixels (7.959mm diagonal)

♦ Chip size : 7.60mm (H) × 6.20mm (V) ♦ Unit cell size : 4.65μm (H) × 4.65μm (V)

◆ Optical black : Horizontal (H) direction : Front 2 pixels, rear 40 pixels

Vertical (V) direction : Front 8 pixels, rear 2 pixels

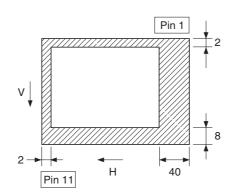
◆ Number of dummy bits : Horizontal 20

Vertical 3

◆ Substrate material : Silicon

Optical Black Position

(Top View)



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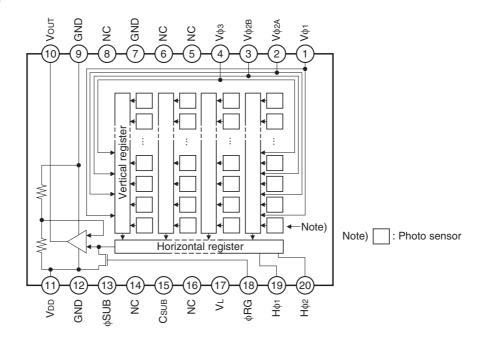
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Block Diagram and Pin Configuration

(Top View)



Pin Description

Pin No.	Symbol	Description	Pin No.	Symbol	Description
1	Vф1	Vertical register transfer clock	11	VDD	Supply voltage
2	Vф2A	Vertical register transfer clock	12	GND	GND
3	V ф2В	Vertical register transfer clock	13	φSUB	Substrate clock
4	Vфз	Vertical register transfer clock	14	NC	
5	NC		15	CsuB	Substrate bias*1
6	NC		16	NC	
7	GND	GND	17	VL	Protective transistor bias
8	NC		18	φRG	Reset gate clock
9	GND	GND	19	Нф1	Horizontal register transfer clock
10	Vоит	Signal output	20	Нф2	Horizontal register transfer clock

 $^{^{*1}~}$ DC bias is generated within the CCD, so that this pin should be grounded externally through a capacitance of 0.1 $\mu\text{F}.$

Absolute Maximum Ratings

	Item	Ratings	Unit	Remarks
	Vdd, Vout, фRG – фSUB	-40 to +10	V	
	V¢2A, V¢2B – ¢SUB	-50 to +15	V	
Against ∳SUB	Vφ1, Vφ3, VL – φSUB	-50 to +0.3	V	
	Hφ1, Hφ2, GND – φSUB	-40 to +0.3	V	
	Csub – \$SUB	–25 to	V	
	VDD, VOUT, фRG, CSUB – GND	-0.3 to +18	V	
Against GND	Vφ1, Vφ2A, Vφ2B, Vφ3 – GND	–10 to +18	V	
	Hφ1, Hφ2 – GND	–10 to +15	V	
Against VL	Vφ2A, Vφ2B – VL	-0.3 to +28	V	
	Vφ1, Vφ3, Hφ1, Hφ2, GND – VL	-0.3 to +15	V	
	Voltage difference between vertical clock input pins	to +15	V	*1
Between input clock pins	Ηφ1 – Ηφ2	-16 to +16	V	
	Hφ1, Hφ2 – Vφ3	-16 to +16	V	
Storage temperatu	-30 to +80	°C		
Operating tempera	-10 to +60	°C		

^{*1 +24}V (Max.) when clock width < 10μ s, clock duty factor < 0.1%.

Bias Conditions

Item	Symbol	Min.	Тур.	Max.	Unit	Remarks
Power Supply voltage	VDD	14.55	15.0	15.45	V	
Protective transistor bias	VL	*1				
Substrate clock	φSUB	*2				
Reset gate clock	φRG	*2				

^{*1} VL setting is the VvL voltage of the vertical transfer clock waveform, or the same power supply as the VL power supply for the V driver should be used.

DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Remarks
Power supply current	IDD		7.7		mA	

⁺¹⁶V (Max.) is guaranteed for turning on or off power supply.

^{*2} Do not apply a DC bias to the substrate clock and reset gate clock pins, because a DC bias is generated within the CCD.

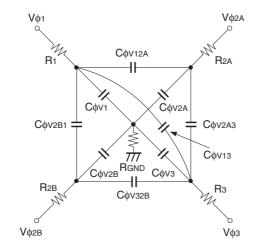


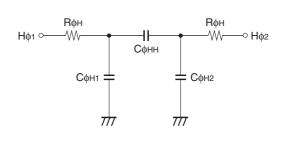
Clock Voltage Conditions

Item	Symbol	Min.	Тур.	Max.	Unit	Waveform diagram	Remarks
Readout clock voltage	Vvт	14.55	15.0	15.45	V	1	
	VvH02A	-0.05	0	0.05	V	2	Vvh = Vvho2A
	Vvh1, Vvh2A, Vvh2B, Vvh3	-0.2	0	0.05	V	2	
	VVL1, VVL2A, VVL2B, VVL3	-8.4	-8.0	-7.6	V	2	VvL = (VvL1 + VvL3)/2
Vertical transfer clock voltage	Vφ1, Vφ2A, Vφ2B, Vφ3	7.6	8.0	8.4	V	2	
	VVL1 – VVL3			0.1	V	2	
	Vvнн			0.9	V	2	High-level coupling
	VVHL			1.3	V	2	High-level coupling
	VVLH			1.0	V	2	Low-level coupling
	VVLL			0.9	V	2	Low-level coupling
Horizontal transfer clock	Vфн	4.75	5.0	5.25	V	3	
voltage	VHL	-0.05	0	0.05	V	3	
	VφRG	3.0	3.3	5.5	V	4	
Reset gate clock voltage	VRGLH – VRGLL			0.4	V	4	Low-level coupling
	VRGL - VRGLm			0.5	V	4	Low-level coupling
Substrate clock voltage	Vфsuв	22.15	23.0	23.85	V	5	

Clock Equivalent Circuit Constant

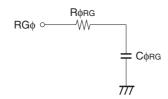
Item	Symbol	Min.	Тур.	Max.	Unit	Remarks
	СфV1		2200		pF	
Capacitance between vertical transfer clock	СфV2А		3300		pF	
and GND	Сф∨2В		3300		pF	
	Сф∨з		3300		pF	
	СфV12A, СфV2В1		1200		pF	
Capacitance between vertical transfer clocks	Сфу2А3, Сфу32В		1200		pF	
	СфV13		2200		pF	
Capacitance between horizontal transfer clock and GND	Сфн1, Сфн2		47		pF	
Capacitance between horizontal transfer clocks	Сфнн		100		pF	
Capacitance between reset gate clock and GND	СфRG		8		pF	
Capacitance between substrate clock and GND	Сфѕив		680		pF	
	R ₁		36		Ω	
Vertical transfer clock series resistor	R2A, R3		56		Ω	
	R ₂ B		56		Ω	
Vertical transfer clock ground resistor	RGND		30		Ω	
Horizontal transfer clock series resistor	Rфн		15		Ω	
Reset gate clock series resistor	Rørg		20		Ω	





Vertical transfer clock equivalent circuit

Horizontal transfer clock equivalent circuit



Reset gate clock equivalent circuit